

Application No. 10/099,870

Filed: March 14, 2002

TC Art Unit: 2825

Confirmation No.: 4461

AMENDMENT TO THE CLAIMS

1. (Currently Amended) An inspection system for process equipment for treating substrates, ~~such as, for instance,~~ semiconductor wafers or flat panel displays, the system being provided with a wireless sensor with which the interior of the process device can be inspected, the sensor being provided with a transmitter to transfer a signal, during inspection of the interior of the process device, to a receiver located outside the process device, the wireless sensor being arranged on a support having substantially the same dimensions as the substrates to be treated, wherein the sensor includes a micro video camera.

2. (Original) An inspection system according to claim 1, wherein, for the purpose of a process device provided with substrate transport means, the wireless sensor is arranged on the support, such that the support can be transported in the process device with said substrate transport means.

3. (Previously Presented) An inspection system according to claim 1, wherein for the wireless communication an infrared technique is used.

4. (Previously Presented) An inspection system according to claim 1, wherein for the wireless communication a radio technique is used.

5. (Original) An inspection system according to claim 4, wherein an antenna for receiving the signal transmitted by the wireless sensor is disposed outside the process device.

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6. (Original) An inspection system according to claim 4, wherein an antenna for receiving the signal transmitted by the wireless sensor is disposed in the interior of the process device.

7. (Original) An inspection system according to claim 4, wherein for the wireless communication the "Bluetooth" technology is used.

8. (Currently Amended) A sensor provided with a transmitter for wireless communication, for inspecting the interior of a process device for treating substrates, the sensor being arranged on a support having substantially the same shape and dimensions as the substrates to be treated, wherein the sensor includes a micro video camera.

9. (Original) A sensor according to claim 8, wherein the sensor is arranged on a silicon wafer.

10. (Cancelled)

11. (Currently Amended) A sensor according to claim 8, wherein the support is provided with two sensors designed as micro video cameras, arranged substantially parallel and at eye distance from each other, so that a stereo image can thereby be obtained.

12. (Currently Amended) A method for inspecting the interior of a process device for treating substrates, wherein the process device is provided with an input/output station for the input/output of substrates, at least one process chamber for treating substrates and substrate transport means to transport the substrates from the

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input/output station to the process chamber and vice versa, wherein a sensor provided with a transmitter is placed on the input/output station and is transported with the substrate transport means to the interior of the process device for performing the inspection, wherein during the inspection the transmitter transmits a signal which can be received with a receiver disposed outside the process device, and wherein after completion of the inspection the sensor is placed on the input/output station again with the substrate transport means, wherein the sensor is a camera and the inspection is a visual inspection.

13. (Cancelled)

14. (Currently Amended) A method according to claim ~~12~~12, wherein programming of the substrate transport mechanism takes place during the visual inspection on the ground of the information supplied by the camera.

15. (Original) A method according to claim 12, wherein adjustment of the process device takes place during inspection on the ground of the information supplied by the sensor.

16. (Previously Presented) An inspection system according to claim 2, wherein for the wireless communication an infrared technique is used.

17. (Previously Presented) An inspection system according to claim 2, wherein for the wireless communication a radio technique is used.